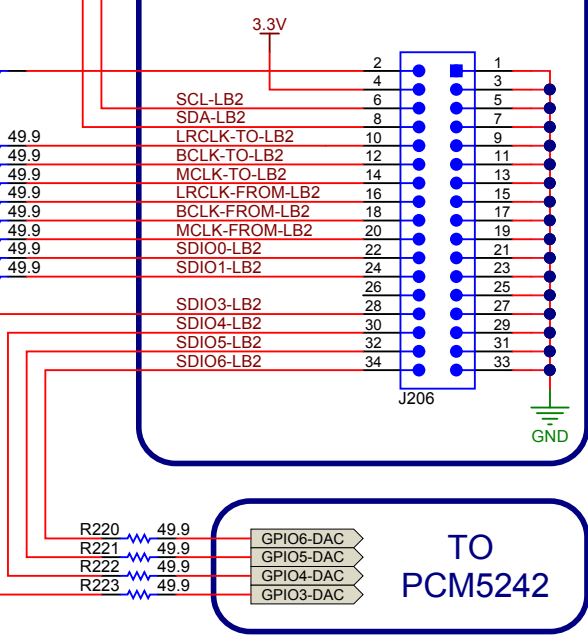
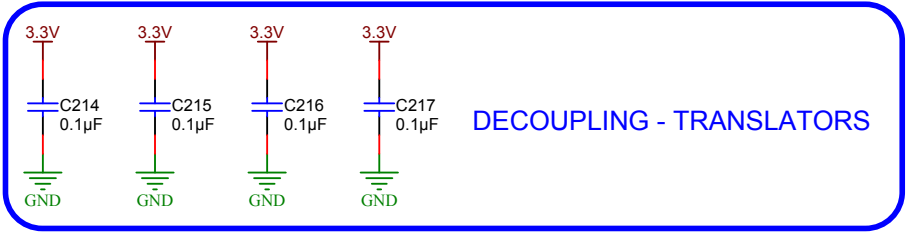
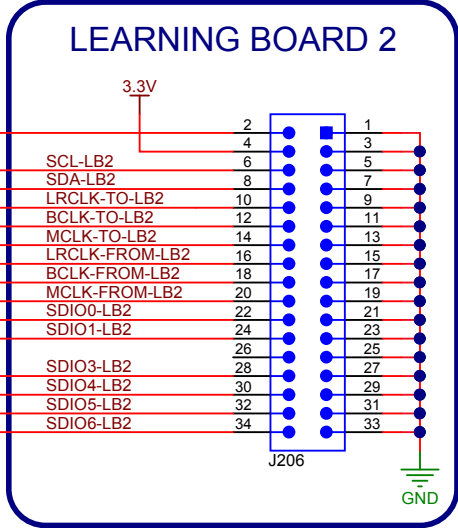
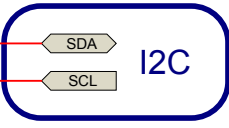
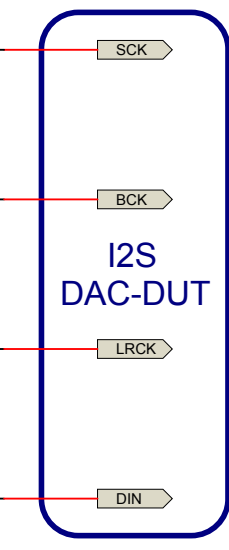
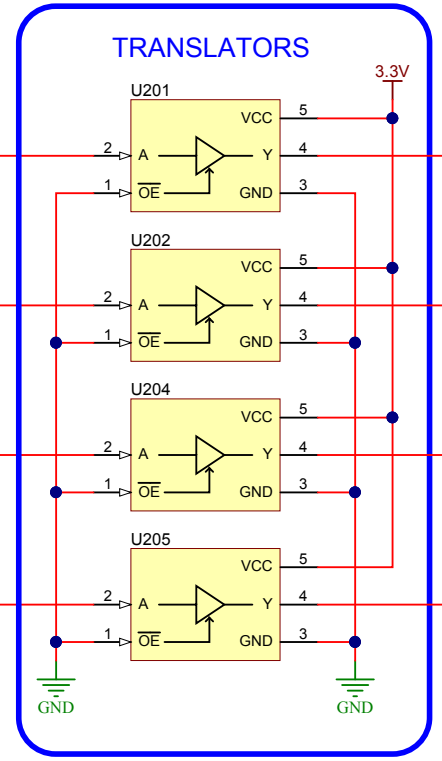
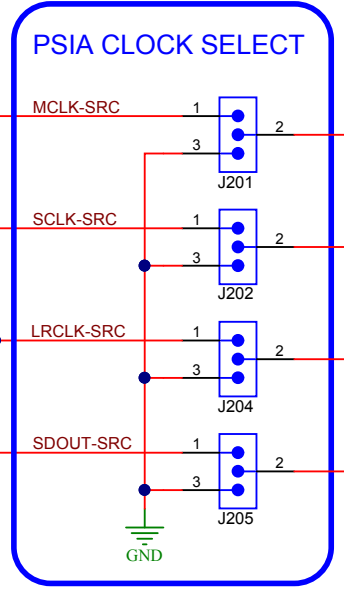
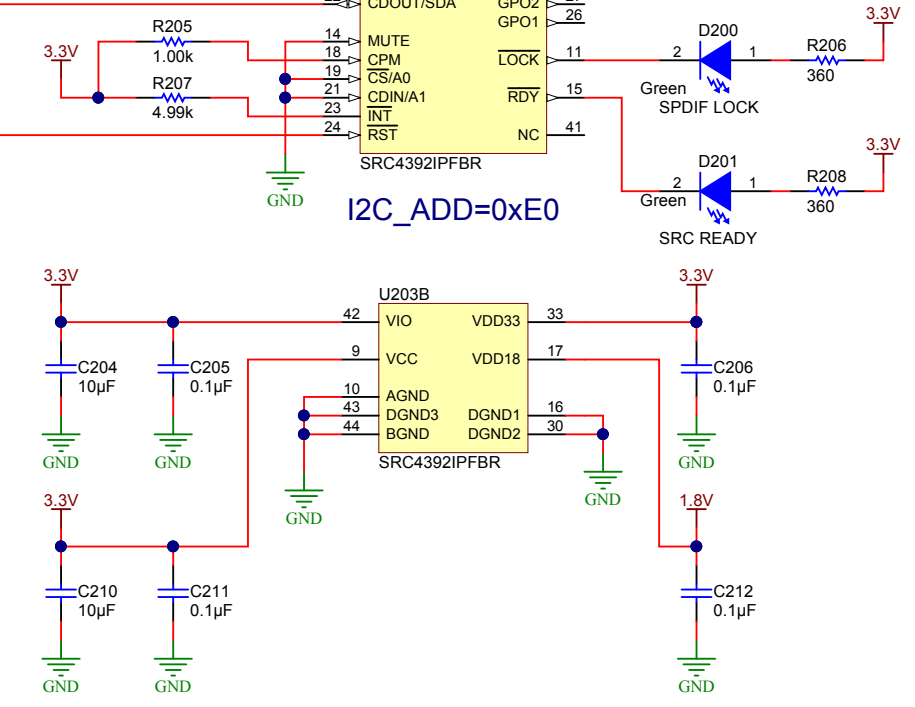
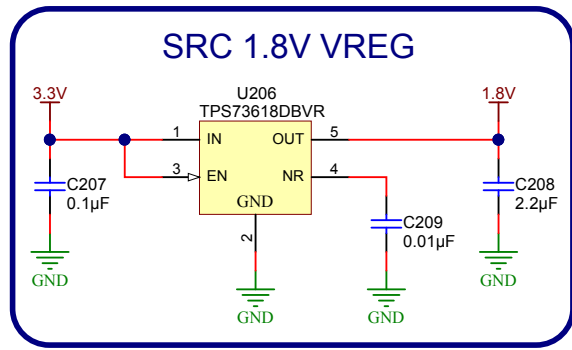
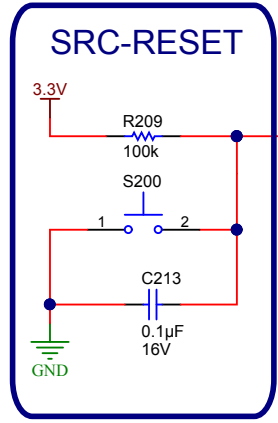
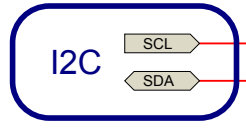
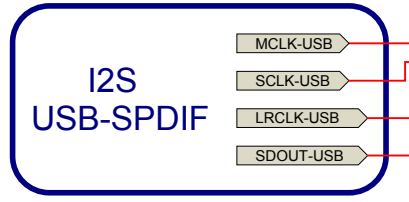
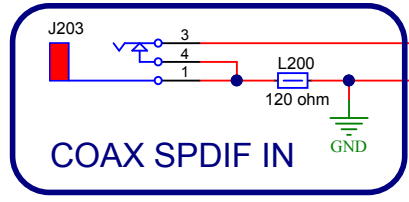
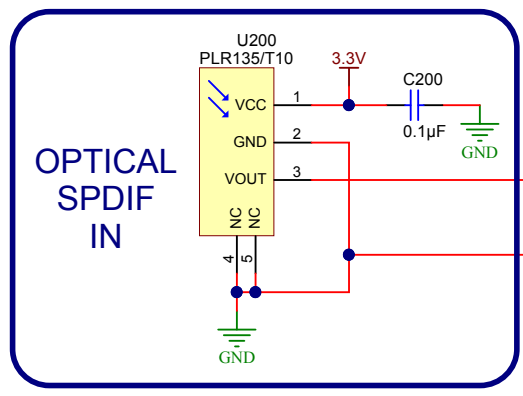


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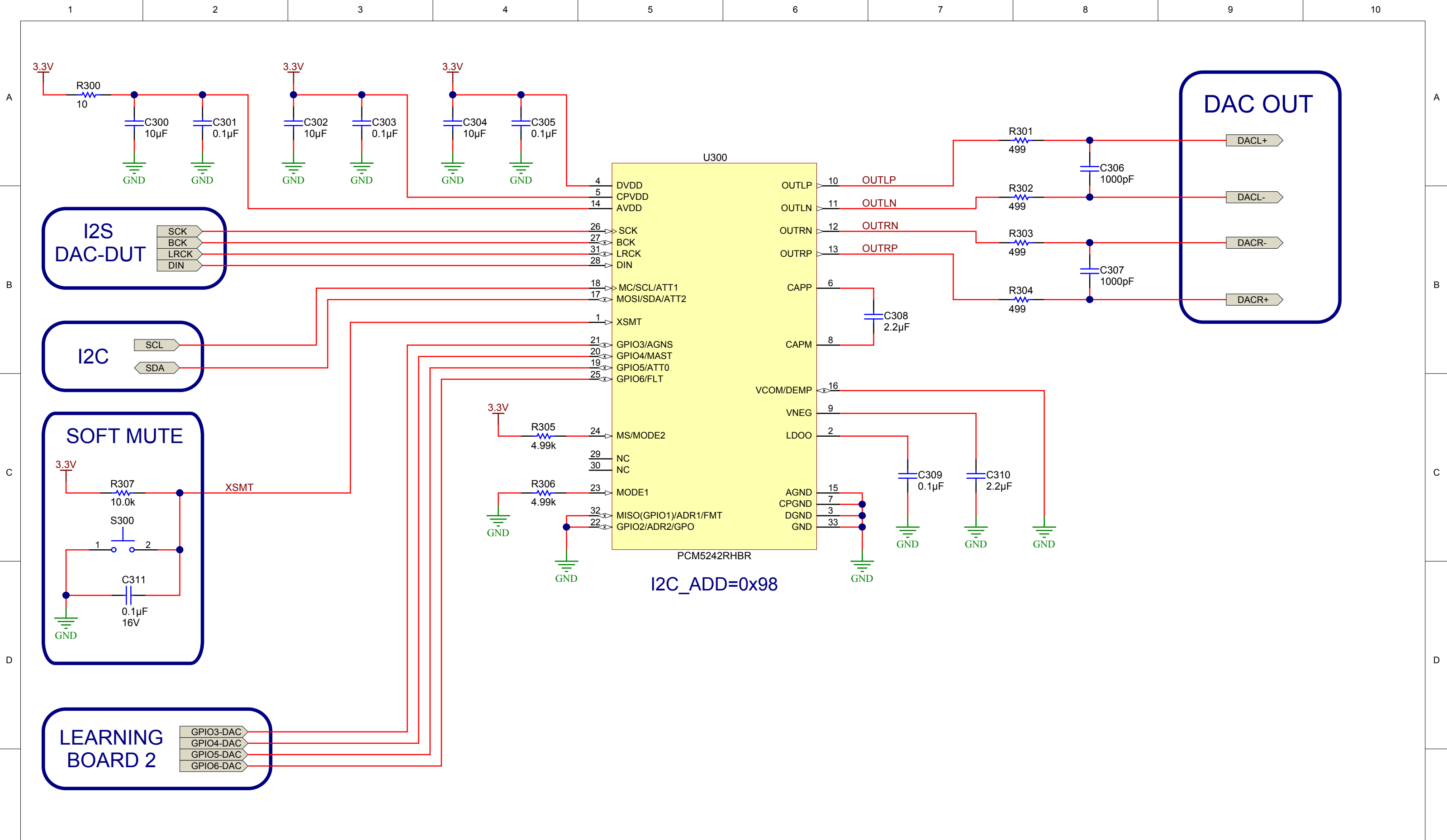
Number: TIDA-00874 Rev: E1  
 SVN Rev: Version control disabled  
 Drawn By: LDN  
 Engineer: Matt Beardsworth

Designed for: Not For Public Release Mod. Date: 12/15/2015  
 Project Title: Hi Fi 175W Class-D Audio Amp with Digital Inputs  
 Sheet Title: USB to I2C/I2S/GPIO Controller Board  
 Assembly Variant: 001  
 File: USB-TAS1020B\_SchDoc  
 Contact: <http://www.ti.com/support>





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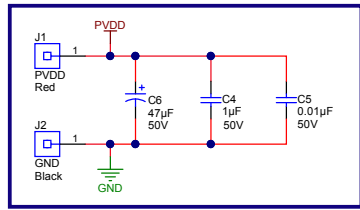


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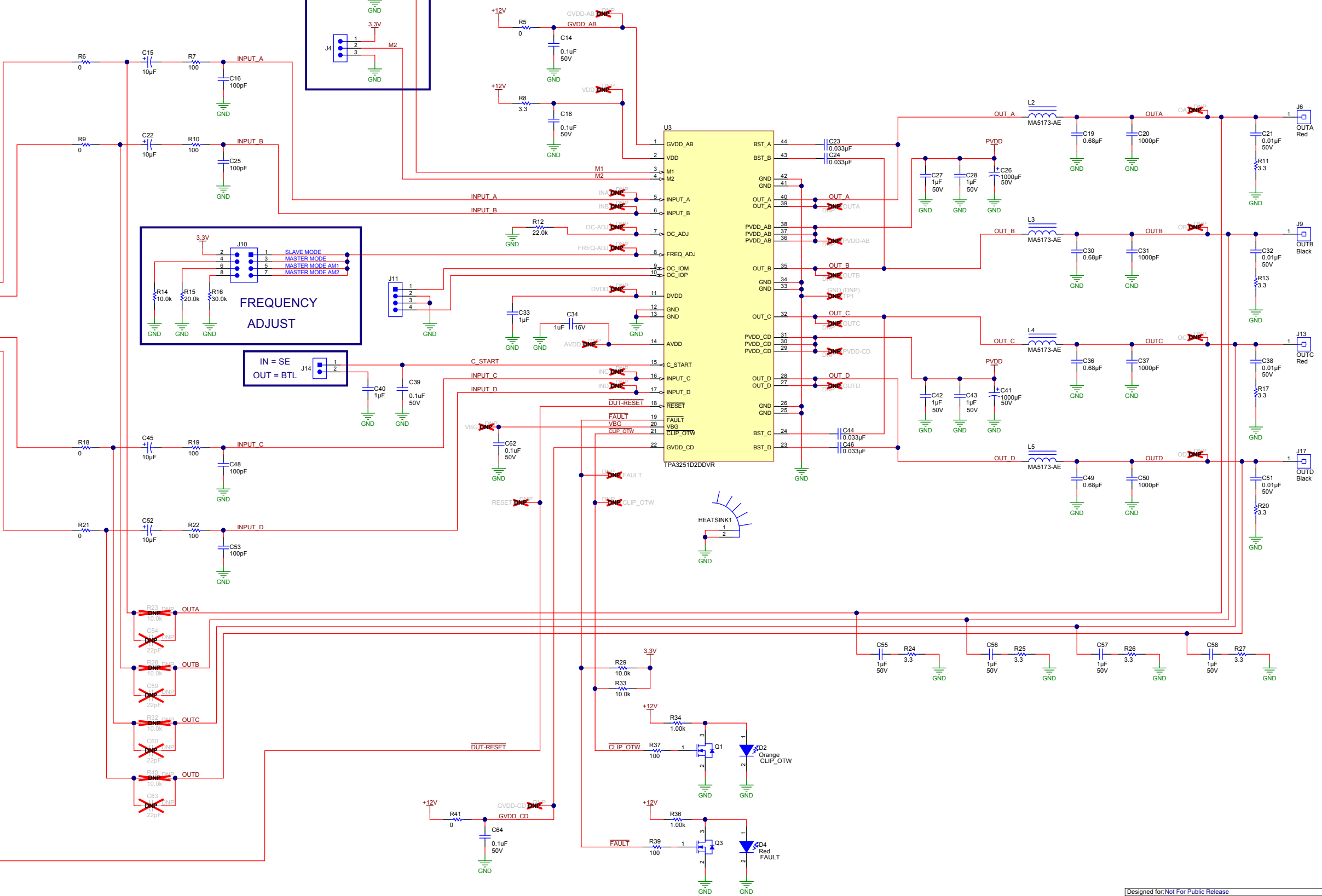
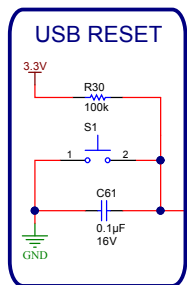
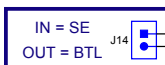
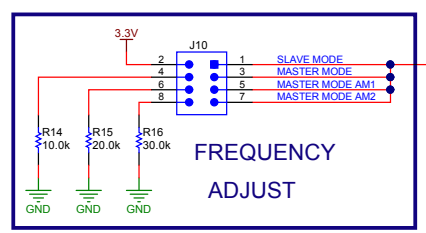
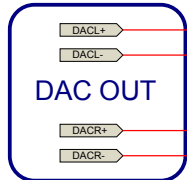
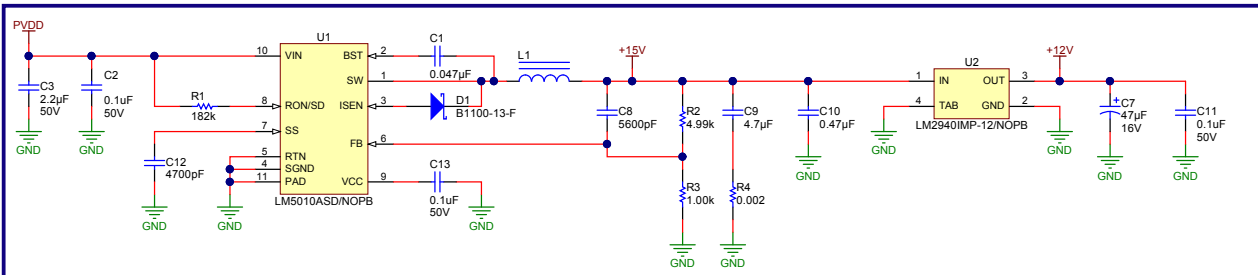
Number: [TIDA-00874](#)  
 SVN Rev: Version control disabled  
 Drawn By: [LDN](#)  
 Engineer: [Matt Beardsworth](#)  
 Sheet: 3 of 5

Designed for: [Not For Public Release](#)  
 Project Title: [Hi Fi 175W Class-D Audio Amp with Digital Inputs](#)  
 Sheet Title: [PCM5142 DAC](#)  
 Assembly Variant: 001  
 File: [DAC-PCM5242\\_SchDoc](#)  
 Contact: <http://www.ti.com/support>  
 Mod. Date: 11/13/2015  
 Size: AB | Rev: E1

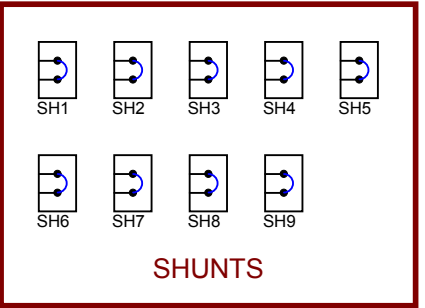
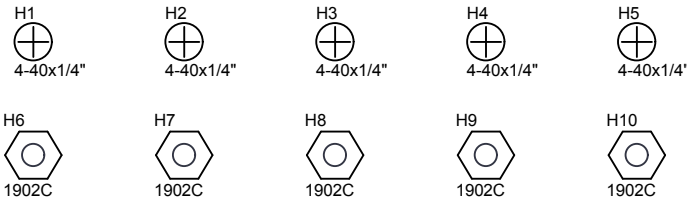




M2	M1	INPUT MODE	OUTPUT	DESCRIPTION
0	0	2N + 1	2xBTL	STEREO BTL OUTPUT, AD MODE
0	1	2N/1N + 1	1xBTL + 2xSE	2.1 BTL + SE MODE, AD MODE
1	0	2N + 1	1xPBTL	PARALLEL BTL OUTPUT, AD MODE
1	1	1N + 1	4xSE	SINGLE ENDED OUTPUT, AD MODE



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**ZZ1**  
**Assembly Note**  
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

**ZZ2**  
**Assembly Note**  
 These assemblies are ESD sensitive, ESD precautions shall be observed.

**ZZ3**  
**Assembly Note**  
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

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TID #: <a href="#">TIDA-00874</a>	Project Title: <b>Hi Fi 175W Class-D Audio Amp with Digital Inputs</b>		
Number: <a href="#">TIDA-00874</a>	Rev: <b>E1</b>	Sheet Title: <b>HARDWARE</b>	
SVN Rev: Version control disabled	Assembly Variant: <b>001</b>	Sheet: <b>5</b> of <b>5</b>	
Drawn By: <b>LDN</b>	File: <b>EVM_Hardware.SchDoc</b>	Size: <b>B</b>	
Engineer: <b>Matt Beardsworth</b>	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		

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